

# PARA LIGHT ELECTRONICS CO., LTD.

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# DATA SHEET

PART NO.: L-C195JRLBCT

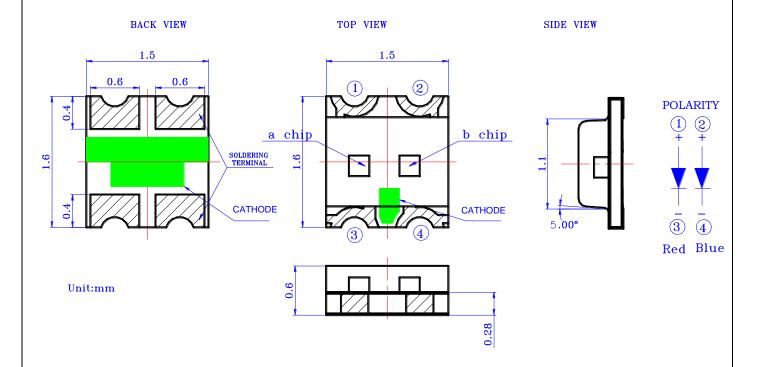
REV: <u>A/5</u>

CUSTOMER'S APPROVAL:	DCC:		
DRAWING NO.: DS-78-14-0003	DATE: 2021-11-26	Page 1	



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#### PACKAGE OUTLINE DIMENSIONS



#### Notes:

- 1. a chip: Red; b chip: Blue
- 2. All dimensions are in millimeters.
- 3. Tolerance is  $\pm$  0.1mm (.004") unless otherwise noted.

#### Features

- \* Dual color, top view, wide view angle Chip LED.
- \* Package in 8mm tape on 7" diameter reels.
- \* Compatible with automatic Pick & Place equipment.
- \* Compatible with Reflow soldering and Wave soldering processes.
- \* EIA STD package.
- \* I.C. compatible.
- \* Pb free product.
- \* Moisture sensitivity level: 3



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# Chip Materials

Chip	Light Color	Dice Material	Lens Color
a	JR: Red	AlInGap	Water Clear
b	LB: Blue	InGaN	Water Clear

# • Absolute Maximum Ratings (Ta=25°C)

Symbol	Symbol Parameter -		Rating	
Symbol			Red	Unit
PD	Power Dissipation	80	75	mW
Inc	IPF Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width) 80		80 80	mA
IPF				
IF	Continuous Forward Current	25	30	mA
VR	Reverse Voltage	5	5	V
ESD	Electrostatic Discharge Threshold (HBM) <sup>Note A</sup>	1000	2000	V
Topr	Topr Operating Temperature Range -40 ~ +85		င့	
Tstg	stg Storage Temperature Range -40 ~ +85		ç	

Note A:

HBM: Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

# • Electro-Optical Characteristics (Ta=25°C)

Parameter		Symbol	Red	Blue	Unit	Test Condit on
	Min.		28	71		IF=20mA
Luminous Intensity	Тур.	IV	40	140	mcd	
	Max.		112	280		
Viewing Angle	Typ.	2θ1/2	1	130		Note 2
	Min.		625	465		
Dominant Wavelength	Typ.	λd	631	470	nm	IF=20mA
	Max.		635	475		
Spectral Line Half-Width	Тур.	Δλ	17	25	nm	
Forward Voltage	Min.		1.7	2.8		
	Тур.	VF	2.0	3.0	V	IF =20mA
	Max.		2.4	3.4		
Reverse Current	Max.	IR	10	50	μA	VR = 5V



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Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2.  $\theta$  1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength  $\lambda$  d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD:
  - Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
- 5. Major standard testing equipment by "Instrument System" Model: CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model: 2400.

### Typical Electro-Optical Characteristics Curves

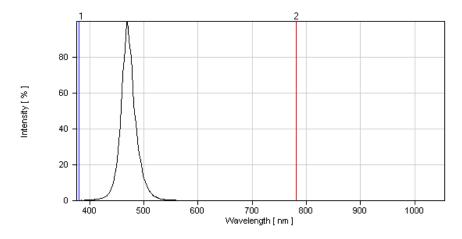


Fig.1 Blue Relative Intensity vs. Wavelength

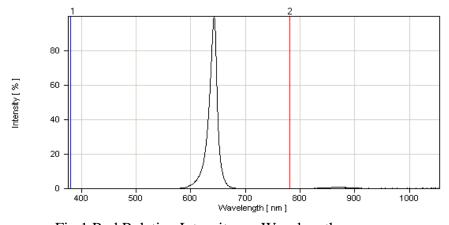


Fig.1 Red Relative Intensity vs. Wavelength



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### Red Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

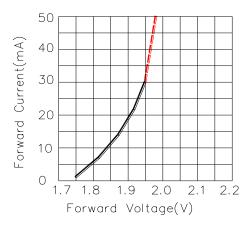


Fig.2 Forward Current vs.Forward Voltage

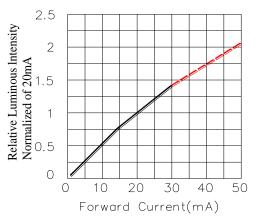


Fig.4 Relative Luminous Intensity vs.Forward Current

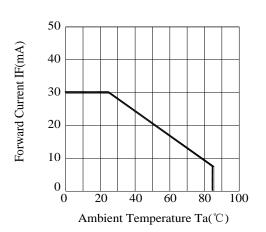


Fig.6 Forward Current Derating Curve

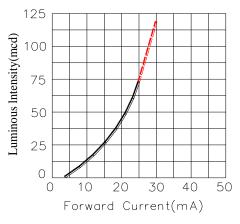


Fig.3 Luminous Intensity vs.Forward Current

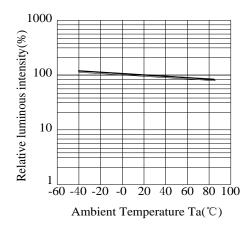


Fig.5 Luminous Intensity vs. Ambient Temperature

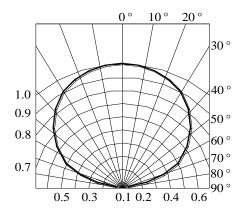


Fig.7 Relative Intensity vs.Angle



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### Blue Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

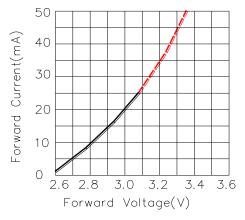


Fig.2 Forward Current vs.Forward Voltage

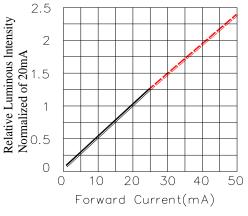


Fig.4 Relative Luminous Intensity vs.Forward Current

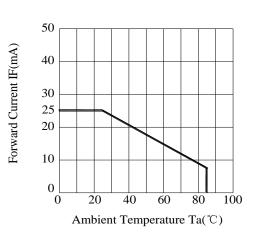


Fig.6 Forward Current Derating Curve

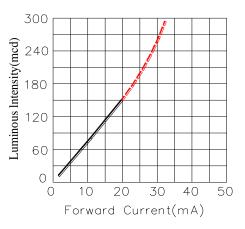


Fig.3 Luminous Intensity vs.Forward Current

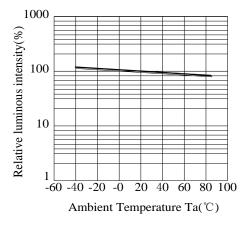


Fig.5 Luminous Intensity vs. Ambient Temperature

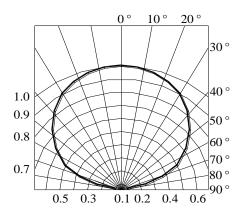


Fig.7 Relative Intensity vs.Angle



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### Label Explanation



ITEM CODE:PARA LIGHT

PART NO: L-C195JRLBCT

IV --- Luminous Intensity Code

LOT NO: EM S L 12 09 0110
A B C D E F

A---EM: Emos Code

B---S:SMD

C---Local

D---Year

E---Month

F---SPEC.

#### PACKING QUANTITY OF BAG:

3000pcs for 150, 170, 110, 155, 115 series

4000pcs for 191 series

5000pcs for 192 series

DATE CODE: <u>2012</u> <u>09</u> <u>10</u>

G H I

G--- Year

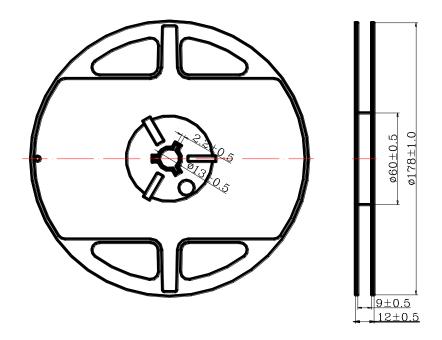
H--- Month

I --- Day



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### Reel Dimensions



#### Notes:

- 1. Taping Quantity: 3000pcs
- 2. The tolerances unless mentioned is  $\pm 0.1$ mm, Angle  $\pm 0.5^{\circ}$ , Unit: mm.

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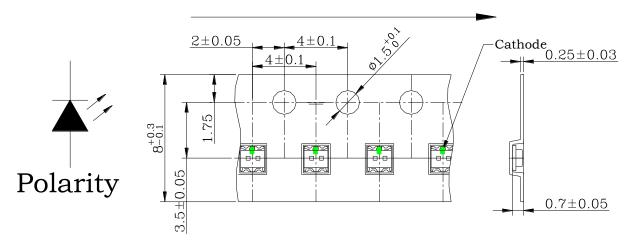


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### Package Dimensions Of Tape And Reel

# Progressive direction

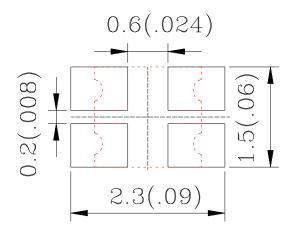


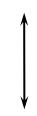
Notes: All dimensions are in millimeters.

### Cleaning

- $\star$  If cleaning is required, use the following solutions for less than 1 minute and less than 40°C.
- \* Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- \* Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

# Suggest Soldering Pad Dimensions





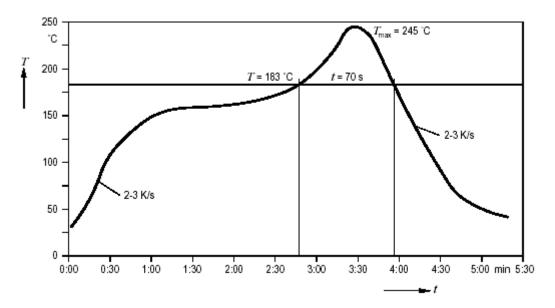
Direction of PWB camber and go to reflow furnace



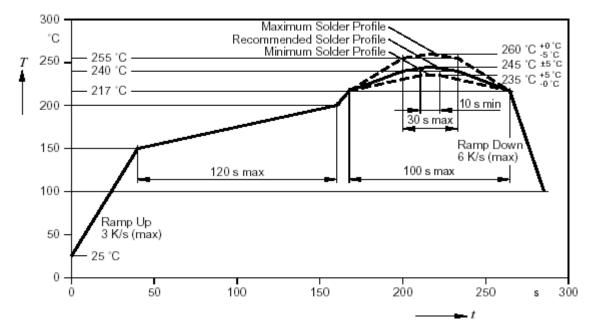
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### • Suggest Sn/Pb IR Reflow Soldering Profile Condition:



### • Suggest Pb-Free IR Reflow Soldering Profile Condition:





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#### Bin Code List

Luminous Intensity (IV), Unit: mcd@20mA					
Red (a chip)		Blue (b chip)			
Bin Code	Min	Max	Bin Code	Min	Max
N	28	45	Q	71	112
P	45	71	R	112	180
Q	71	112	S	180	280

#### Tolerance of each bin are $\pm 15\%$

Forward Voltage(VF), Unit:V@20mA				
	Blue (b chip)			
Bin Code Min Max				
K8	2.8	2.95		
K9	2.95	3.10		
K10	3.10	3.25		
K11	3.25	3.40		

Tolerance of each bin are  $\pm 0.1$  Volt

Dominant Wavelength (Hue), Unit: nm@20mA			
Blue (b chip)			
Bin Code	Min	Max	
AC	465	470	
AD	470	475	

Tolerance of each bin are ± 1nm

#### **CAUTIONS**

#### 1. Application Limitation:

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

#### 2.Storage:

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours



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#### 3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering:

Pre-heat 120~150 ℃, 120sec. MAX., Peak temperature: 240 ℃ Max. Soldering time: 10 sec Max.

Soldering Iron: (Not recommended)

Temperature 300 °C Max., Soldering time: 3 sec. Max.(one time only), power dissipation of iron: 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering:

Pre-heat 100 °C Max, Pre-heat time 60 sec. Max, Solder wave 260 °C Max, Soldering time 5 sec. Max. preformed consecutively cooling process is required between 1<sup>st</sup> and 2<sup>nd</sup> soldering processes.

#### 4. Lead-Free Soldering

For Reflow Soldering:

- 1. Pre-Heat Temp:150-180°C,120sec.Max.
- 2. Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3 Peak Temperature: 260 °C , 5 sec.
- 4. Reflow Repetition:2 Times Max.
- 5. Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

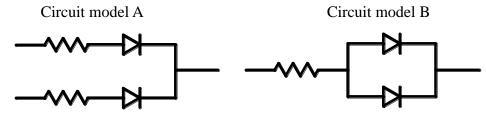
For Soldering Iron (Not Recommended):

- 1. Iron Tip Temp:350°C Max.
- 2. Soldering Iron:30w Max.
- 3. Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering:

- 1. Pre-Heat Temp:150°C Max. 120 Sec. Max.
- 2. Bath Temp:265°C Max.
- 3. Dip Time: 5 Sec. Max.

#### 5. Drive Method



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.